

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
Nicola Vannucci		07/05/2007
Hubert Maier		07/05/2007
RECEIVING PARTY DATA		
Name:	Infineon Technologies Austria AG	
Street Address:	Siemensstr. 2	
City:	Villach	
State/Country:	AUSTRIA	
Postal Code:	9500	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	11767060	
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ATTORNEY DOCKET NUMBER:	I436.153.101/IO070603PUS	
NAME OF SUBMITTER:	Steven E. Dicke	
Total Attachments: 1		
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PATENT  
REEL: 019771 FRAME: 0342

### ASSIGNMENT

For good and valuable consideration, I, Nicola Vannucci, a citizen of Italy, residing at Federaunerstrasse 22, 9586 Fuernitz, Austria; and Hubert Maier, a citizen of Austria, residing at Herbert-Strutz-Str. 5, 9500 Villach, Austria, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies Austria AG**, a corporation, organized and existing under the laws of Germany, having its principal place of business at Siemensstrasse 2, 9500 Villach, Austria, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and was filed on June 22, 2007 as U.S. Application No. 11/767,060, entitled:

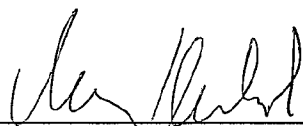
#### **METHOD OF FORMING A SEMICONDUCTOR STRUCTURE COMPRISING INSULATING LAYERS WITH DIFFERENT THICKNESSES**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE:  DATE: 05/7/2007  
NAME: Nicola Vannucci

SIGNATURE:  DATE: 05.07.2007  
NAME: Hubert Maier